WEBENCH® Allegro Connector

Mansour, Makram

ABSTRACT

The purpose of this document is to provide information on the features available in this release of WEBENCH Allegro Connector. It also contains details about the known issues and limitations of this software.

Contents

All trademarks are the property of their respective owners.

1 Feature Available

- Import WEBENCH Designs
- Integration with latest release of Allegro 16.6
- GUI to create and edit WBSE simulation setting files
- One-click solution to provide optimised settings for PSpice models with Abrupt transitions
- WBSE version used is 4.2.3
- Supports installation in path with spaces. For example in Program Files
- Supports the Allegro Projects paths with spaces
- Start Menu entries are unified under Texas Instruments directory
- Supports importing simulation settings from existing Pspice SIM file
- Saving WBSE simulation settings with Allegro Project
- Updated documentation. Help documentation is available in CHM and PDF formats.
- New simulation status UI

2 Fixed/New in this Release

2.1 c1.3.2-s.4.2.3

- Added Import WEBENCH xml feature
- Added more WEBENCH Designer links
- Updated the User Guide and 'About' info
- Rearranged WEBENCH menu item for 16.6

2.2 RC3

- Fixed issue with path
- Old Simulation profile is not working
- Make flow consistent with DAT file format
- Window do not resize properly while changing the analysis
- Make Capture free when WBSE simulation is running
- Bind Enter and Esc key to the UI
- Custom/Additional options are not getting cleared when a new simulation profile is created
- Simulation profile is not getting deleted
- Simulation is not running, and no command window opens up
- UI does not come up when multiple projects are open and at least one of them does not have any simulation profile.

2.3 RC2

- View waveform function is fixed

2.4 RC1

- Capability for generating WEBENCH netlist, usable by CIR2TIS Perl script
- UI controls provided for OPTSTEP, TSTEP and LTERELRATIO

2.5 RC

- GUI generated netlists are compatible to cir2tis generated netlists
- Toolbar icons have been updated to graphical icons
- Issue with toolbar in SPB 16.6 have been fixed (Cadence).

3 Beta 4

- PSpice Markers are supported. Currently markers can be placed only on the top level designs.
- WBSE version upgraded to 4.2.1
- Direct DAT file generation is supported in WBSE, which reduces simulation viewing time significantly. Currently it is supported for Allegro SPB 16.3 and SPB 16.5.
-

4 Beta 3

- Enable library is integrated with WEBENCH Allegro Connector installer
- Enable library documentation is integrated
- WBSE User Manual is integrated in WEBENCH Allegro Installer

5 Beta 2.3

- Fixed issue with improper lib file getting added in project reload. Extension was getting removed from filename.
- Enhanced UI with option to select N number of level to select nodes for plotting
- A GUI button is added to reset the simulation settings to default settings
- Toolbar for Allegro 16.6 is removed due to Allegro crash issue. Will be enable after next hotfix release from Cadence.
- Active simulation profile is loaded with the project. User can directly run the simulation if a profile is already saved.
- Fixed issue with LIB files (with name as -1) getting added when user clicks cancel button.
- Fixed the bug regarding improper netlisting when multiple projects are open.

6 Known Issues

- View Simulation Results do not work if any instance of AMS simulator is already opened
- WEBENCH menu items may appear out of sequence while using Allegro 16.5

7 Future Enhancements

- Using already opened instance of AMS simulator to view simulation results
- TI logo for TI ICs
- Correct pin name locations for ICs
- Num CPU option in GUI
- Activate the connector from within Allegro
- Check for Updates for the connector
- Support for isspice parts
- Support WEBNCH import for Filter/Amplifier designs (AC analysis)

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have *not* been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products		**Applications**	
Audio	www.ti.com/audio	Automotive and Transportation	www.ti.com/automotive
Amplifiers	amplifier.ti.com	Communications and Telecom	www.ti.com/communications
Data Converters	dataconverter.ti.com	Computers and Peripherals	www.ti.com/computers
DLP® Products	www.dlp.com	Consumer Electronics	www.ti.com/consumer-apps
DSP	dsp.ti.com	Energy and Lighting	www.ti.com/energy
Clocks and Timers	www.ti.com/clocks	Industrial	www.ti.com/industrial
Interface	interface.ti.com	Medical	www.ti.com/medical
Logic	logic.ti.com	Security	www.ti.com/security
Power Mgmt	power.ti.com	Space, Avionics and Defense	www.ti.com/space-avionics-defense
Microcontrollers	microcontroller.ti.com	Video and Imaging	www.ti.com/video
RFID	www.ti-rfid.com		
OMAP Applications Processors	www.ti.com/omap	**TI E2E Community**	e2e.ti.com
Wireless Connectivity	www.ti.com/wirelessconnectivity		

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2015, Texas Instruments Incorporated